| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| S1 | 1415 | 257/738.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 20:57 |
| S2 | 373 | S1 and resist | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 20:50 |
| S3 | 18 | S2 and (die adj pad) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 20:54 |
| S4 | 38 | S2 and (die near3 pad) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 20:54 |
| S5 | 20 | S4 not S3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 20:55 |
| S6 | 1692 | 257/737.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 20:57 |
| S7 | 468 | S6 and resist | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 20:57 |
| S8 | 37 | S7 and (die near3 pad) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 20:58 |
| S9 | 14 | S8 not S4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 20:58 |

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| S10 | 14 | S9 not S3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 21:01 |
| S11 | 3 | (die near3 pad) and ((external near3 (lead or terminal or electrode or solder)) same ((opening or void) near3 resist)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/05/04 15:41 |
| S12 | 2875 | 257/758.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 20:46 |
| S13 | 177 | (semiconductor or die or ic or chip or (integrated adj circuit)) and (solder or brazing) and (plate or plating) and (die adj pad) and (bonding adj pad) and (resin or epoxy or encapsulant) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 13:21 |
| S14 | 630 | 257/782.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 17:21 |
| S15 | 2117 | 257/778.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 14:52 |
| S16 | 924 | 257/783.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 14:52 |
| S17 | 1763 | 257/784.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 14:52 |
| S18 | 419 | 257/772.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 14:53 |
| S19 | 1415 | 257/738.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 14:53 |

| S20 | 3353 | 257/787.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 14:53 |
|---|---|---|---|---|---|---|
| S21 | 1482 | 257/700.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 14:53 |
| S22 | 2875 | 257/758.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 14:53 |
| S23 | 12321 | 257/782.ccls. or 257/778.ccls. or 257/783.ccls. or 257/784.ccls. or 257/772.ccls. or 257/738.ccls. or 257/787.ccls. or 257/700.ccls. or 257/758.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 14:54 |
| S24 | 5461 | (257/782.ccls. or 257/778.ccls. or 257/783.ccls. or 257/784.ccls. or 257/772.ccls. or 257/738.ccls. or 257/787.ccls. or 257/700.ccls. or 257/758.ccls.) and (solder or brazing or ag) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 14:54 |
| S25 | 2761 | ((257/782.ccls. or 257/778.ccls. or 257/783.ccls. or 257/784.ccls. or 257/772.ccls. or 257/738.ccls. or 257/787.ccls. or 257/700.ccls. or 257/758.ccls.) and (solder or brazing or ag)) and (plate or plating) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 14:55 |
| S26 | 4338 | ((257/782.ccls. or 257/778.ccls. or 257/783.ccls. or 257/784.ccls. or 257/772.ccls. or 257/738.ccls. or 257/787.ccls. or 257/700.ccls. or 257/758.ccls.) and (solder or brazing or ag)) and (bond or bonding) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 14:56 |
| S27 | 2301 | (((257/782.ccls. or 257/778.ccls. or 257/783.ccls. or 257/784.ccls. or 257/772.ccls. or 257/738.ccls. or 257/787.ccls. or 257/700.ccls. or 257/758.ccls.) and (solder or brazing or ag)) and (plate or plating)) and (bond or bonding) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 14:56 |

| S28 | 1893 | (((((257/782.ccls. or 257/778.ccls. or 257/783.ccls. or 257/784.ccls. or 257/772.ccls. or 257/738.ccls. or 257/787.ccls. or 257/700.ccls. or 257/758.ccls.) and (solder or brazing or ag)) and (plate or plating)) and (bond or bonding)) and (encapsulant or resin or epoxy) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 14:57 |
|---|---|---|---|---|---|---|
| S29 | 1841 | (((((257/782.ccls. or 257/778.ccls. or 257/783.ccls. or 257/784.ccls. or 257/772.ccls. or 257/738.ccls. or 257/787.ccls. or 257/700.ccls. or 257/758.ccls.) and (solder or brazing or ag)) and (plate or plating)) and (bond or bonding)) and (encapsulant or resin or epoxy)) not ((semiconductor or die or ic or chip or (integrated adj circuit)) and (solder or brazing) and (plate or plating) and (die adj pad) and (bonding adj pad) and (resin or epoxy or encapsulant)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2004/09/24 14:59 |
| S35 | 6586 | (semiconductor or chip or die or ic or (integrated adj circuit)) and (die near3 pad) and (lead or terminal or electrode or solder or pad) and (resin or encapsulant or epoxy) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/05/04 15:45 |
| S36 | 2850 | "257"/$6.ccls. and ((semiconductor or chip or die or ic or (integrated adj circuit)) and (die near3 pad) and (lead or terminal or electrode or solder or pad) and (resin or encapsulant or epoxy)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/05/04 16:30 |
| S37 | 1698 | "257"/$6.ccls. and ((semiconductor or chip or die or ic or (integrated adj circuit)) and (die near3 pad) and (lead or terminal or electrode or solder or pad) and (resin or encapsulant or epoxy)) | USPAT | OR | OFF | 2005/05/05 12:41 |
| S38 | 52 | "257"/$6.ccls. and ((semiconductor or chip or die or ic or (integrated adj circuit)) and (die near3 pad) and (lead or terminal or electrode or solder or pad) and (resin or encapsulant or epoxy) and dummy) | USPAT | OR | OFF | 2005/05/04 16:29 |

| S39 | 88 | "257"/$6.ccls. and ((semiconductor or chip or die or ic or (integrated adj circuit)) and (die near3 pad) and (lead or terminal or electrode or solder or pad) and (resin or encapsulant or epoxy) and dummy) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/05/04 16:30 |
|-----|-----|-----|-----|-----|-----|-----|
| S40 | 1 | ("6501162").PN. | USPAT | OR | OFF | 2005/05/05 12:36 |
| S41 | 351 | "257"/$6.ccls. and ((semiconductor or chip or die or ic or (integrated adj circuit)) and (die near3 pad) and (lead or terminal or electrode or solder or pad) and (resin or encapsulant or epoxy)) | EPO; JPO; DERWENT | OR | OFF | 2005/05/05 12:41 |
| S42 | 1 | "6459549".PN. | USPAT; USOCR | OR | OFF | 2005/05/05 12:53 |
| S43 | 1 | "6001671".PN. | USPAT; USOCR | OR | OFF | 2005/05/05 12:53 |
| S44 | 772 | 257/782.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 17:29 |
| S45 | 1 | ("6646331").PN. | USPAT | OR | OFF | 2005/12/15 17:29 |
| S46 | 1 | ("6975022").PN. | USPAT | OR | OFF | 2005/12/15 17:30 |
| S47 | 1 | ("6501162").PN. | USPAT | OR | OFF | 2005/12/15 17:30 |
| S48 | 1 | ("6963126").PN. | USPAT | OR | OFF | 2005/12/15 17:30 |
| S49 | 1 | ("6624511").PN. | USPAT | OR | OFF | 2005/12/15 17:31 |
| S50 | 1 | ("6548328").PN. | USPAT | OR | OFF | 2005/12/15 17:32 |
| S51 | 1 | ("6562660").PN. | USPAT | OR | OFF | 2005/12/15 17:32 |
| S52 | 1 | ("6545364").PN. | USPAT | OR | OFF | 2005/12/15 20:25 |
| S53 | 649 | (semiconductor or ic or chip or die or (integrated adj circuit)) and (die adj pad) and ((bond or bonding) near2 pad) and (plated or plating) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 21:50 |
| S54 | 585 | S53 and (encapsulant or encapsulating or encapsulated or resin or epoxy) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 21:51 |

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|---|---|---|---|---|---|---|
| S55 | 64 | S53 not S54 | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/12/15 21:42 |
| S56 | 0 | "E23.""031".ccls. | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/12/15 21:43 |
| S57 | 3 | "E23.031" | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/12/15 21:43 |
| S58 | 0 | "E23.032" | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/12/15 21:43 |
| S59 | 1 | "E23.033" | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/12/15 21:44 |
| S60 | 1 | "E23.034" | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/12/15 21:44 |
| S61 | 1 | "E23.037" | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/12/15 21:44 |
| S62 | 1 | "E23.038" | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2005/12/15 21:44 |

| S63 | 0 | "E23.004" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 21:44 |
|---|---|---|---|---|---|---|
| S64 | 1 | "E23.04" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 21:44 |
| S65 | 3 | "E23.066" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 21:44 |
| S66 | 2 | "E23.068" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 21:44 |
| S67 | 0 | "E23.003" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 21:44 |
| S68 | 0 | "E23.01" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 21:44 |
| S69 | 3 | "E23.015" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 21:44 |
| S70 | 2 | "E23.02" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 21:44 |

| S71 | 0 | "E23.023" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 21:45 |
|-----|-----|-----------|---------|-----|-----|-----------------|
| S72 | 0 | "E23.026" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 21:45 |
| S73 | 15 | S56 S57 S58 S59 S60 S61 S62 S63 S64 S65 S66 S67 S68 S69 S70 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 21:45 |
| S74 | 1753 | (semiconductor or ic or chip or die or (integrated adj circuit)) and (die adj pad) and ((bond or bonding) near2 pad) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 21:51 |
| S75 | 2927 | (semiconductor or ic or chip or die or (integrated adj circuit)) and (die adj pad) and ((bond or bonding) near2 pad) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/15 23:17 |
| S76 | 2278 | S75 not S53 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/15 21:51 |
| S77 | 1564 | S76 and (encapsulant or encapsulating or encapsulated or resin or epoxy) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 23:00 |
| S78 | 714 | S76 not S77 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/15 23:00 |

| S79 | 702 | (semiconductor or ic or chip or die or (integrated adj circuit)) and (die adj paddle) and ((bond or bonding) near2 pad) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/15 23:17 |
|-----|-----|------|------|----|----|------|
| S80 | 723 | (semiconductor or ic or chip or die or (integrated adj circuit)) and (die adj paddle) and ((bond or bonding) near2 (pad or paddle)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/15 23:17 |
| S81 | 621 | S80 not S75 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/15 23:17 |